

14230 U.S.PTO
112003PATENT APPLICATION
Docket No. 9903-070
Client No. S02US037

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

EXPRESS MAIL	MAILING LABEL NO. <u>EL982132725US</u>
	DATE OF DEPOSIT: <u>NOVEMBER 20, 2003</u>
<p>I HEREBY CERTIFY THAT THIS PAPER AND ENCLOSURES AND/OR FEE ARE BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE "EXPRESS MAIL POST OFFICE TO ADDRESSEE" SERVICE UNDER 37 CFR 1.10 ON THE DATE INDICATED ABOVE AND IS ADDRESSED TO: MAIL STOP PATENT APPLICATION, COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450.</p> <p><u>HILLARY A. DIXON</u> (SENDER'S PRINTED NAME)</p> <p> (SIGNATURE)</p>	

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Enclosed for filing is a patent application under 37 CFR 1.53(b) of:

Inventor(s): Hee-Jin Park, Tae-Jin Park and Eun-Chul Ahn

For: STACKED CHIP PACKAGE WITH HEAT TRANSFER WIRES

Applicant requests FIG. 4 to be published with the application.

Enclosures:

- Specification (pages 1-6); claims (pages 7-9); abstract (page 10)
- FOUR sheet(s) of FORMAL drawings (comprising 8 figures)
- Certified copy of Priority Document No. 2002-72256, filed November 20, 2002, from which priority is claimed.
- PTO form 1449 Information Disclosure Statement with 5 cited references.
- Return Postcard

<u>CLAIMS AS FILED</u>				
For	Number Filed	Number Extra	Rate	Basic Fee
Total Claims	20-20	0	x \$ 18 =	\$0.00
Independent Claims	2-3	0	x \$ 86 =	\$0.00
TOTAL FILING FEE				\$770.00

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112003

Combined Declaration and Power of Attorney (unsigned)
 Assignment with cover sheet
Assignee Name and Address: Samsung Electronics Co., Ltd.
Suwon-city, Kyungki-do Republic of Korea

Customer No. 20575

Respectfully submitted,

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